

Power MOSFET



P-Channel MOSFET

FEATURES

- Surface-mount
- Available in tape and reel
- Dynamic dv/dt rating
- Repetitive avalanche rated
- P-channel
- Fast switching
- Ease of paralleling
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE
Available

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The SOT-223 package is designed for surface-mount using vapor phase, infrared, or wave soldering techniques. Its unique package design allows for easy automatic pick-and-place as with other SOT or SOIC packages but has the added advantage of improved thermal performance due to an enlarged tab for heatsinking. Power dissipation of greater than 1.25 W is possible in a typical surface mount application.

Marking code: FF

PRODUCT SUMMARY		
V_{DS} (V)	-100	
$R_{DS(on)}$ (Ω)	$V_{GS} = -10$ V	1.2
Q_g max. (nC)	8.7	
Q_{gs} (nC)	2.2	
Q_{gd} (nC)	4.1	
Configuration	Single	

ORDERING INFORMATION	
Package	SOT-223
Lead (Pb)-free and halogen-free	SiHFL9110TR-GE3 ^a IRFL9110TRPbF-BE3 ^{a, b}
Lead (Pb)-free	IRFL9110TRPbF ^a

Notes

- See device orientation
- “-BE3” denotes alternate manufacturing location

ABSOLUTE MAXIMUM RATINGS ($T_C = 25$ °C, unless otherwise noted)				
PARAMETER	SYMBOL		LIMIT	UNIT
Drain-source voltage	V_{DS}		-100	V
Gate-source voltage	V_{GS}		± 20	
Continuous drain current	V_{GS} at -10 V	$T_C = 25$ °C	-1.1	A
		$T_C = 100$ °C	-0.69	
Pulsed drain current ^a	I_{DM}		-8.8	W/°C
Linear derating factor			0.025	
Linear derating factor (PCB mount) ^e			0.017	
Single pulse avalanche energy ^b	E_{AS}		100	mJ
Avalanche current ^a	I_{AR}		-1.1	A
Repetitive avalanche energy ^a	E_{AR}		0.31	mJ
Maximum power dissipation	$T_C = 25$ °C		3.1	W
Maximum power dissipation (PCB mount) ^e	$T_A = 25$ °C			
Peak diode recovery dv/dt ^c	dv/dt		-5.5	V/ns
Operating junction and storage temperature range	T_J, T_{stg}		-55 to +150	°C
Soldering recommendations (peak temperature) ^d	For 10 s		300	

Notes



- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- $V_{DD} = -25$ V, starting $T_J = 25$ °C, $L = 7.7$ mH, $R_g = 25$ Ω , $I_{AS} = -4.4$ A (see fig. 12)
- $I_{SD} \leq -4.4$ A, $di/dt \leq -75$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 150$ °C
- 1.6 mm from case
- When mounted on 1" square PCB (FR-4 or G-10 material)



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT
Maximum junction-to-ambient (PCB mount) ^a	R _{thJA}	-	-	60	°C/W
Maximum junction-to-case (drain)	R _{thJC}	-	-	40	

Note

a. When mounted on 1" square PCB (FR-4 or G-10 material)

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA		-100	-	-	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = -1 mA		-	-0.091	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA		-2.0	-	-4.0	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = -100 V, V _{GS} = 0 V		-	-	-100	μA
		V _{DS} = -80 V, V _{GS} = 0 V, T _J = 125 °C		-	-	-500	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = -10 V	I _D = -0.66 A ^b	-	-	1.2	Ω
Forward transconductance	g _{fs}	V _{DS} = -50 V, I _D = -0.66 A		0.82	-	-	S
Dynamic							
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = -25 V, f = 1.0 MHz, see fig. 5		-	200	-	pF
Output capacitance	C _{oss}			-	94	-	
Reverse transfer capacitance	C _{rss}			-	18	-	
Total gate charge	Q _g	V _{GS} = -10 V	I _D = -4.0 A, V _{DS} = -80 V, see fig. 6 and 13 ^b	-	-	8.7	nC
Gate-source charge	Q _{gs}			-	-	2.2	
Gate-drain charge	Q _{gd}			-	-	4.1	
Turn-on delay time	t _{d(on)}	V _{DD} = -50 V, I _D = -4.0 A, R _g = 24 Ω, R _D = 11 Ω, see fig. 10 ^b		-	10	-	ns
Rise time	t _r			-	27	-	
Turn-off delay time	t _{d(off)}			-	15	-	
Fall time	t _f			-	17	-	
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact 		-	4.0	-	nH
Internal source inductance	L _S			-	6.0	-	
Drain-Source Body Diode Characteristics							
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	-1.1	A
Pulsed diode forward current ^a	I _{SM}			-	-	-8.8	
Body diode voltage	V _{SD}	T _J = 25 °C, I _S = -1.1 A, V _{GS} = 0 V ^b		-	-	-5.5	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = -4.0 A, dI/dt = 100 A/μs ^b		-	80	160	ns
Body diode reverse recovery charge	Q _{rr}			-	0.15	0.30	μC
Forward turn-on time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

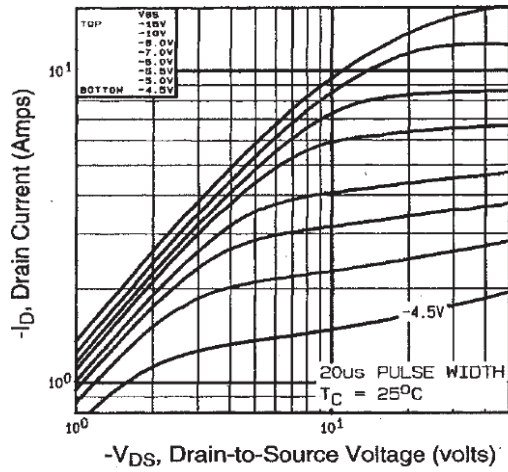


Fig. 1 - Typical Output Characteristics

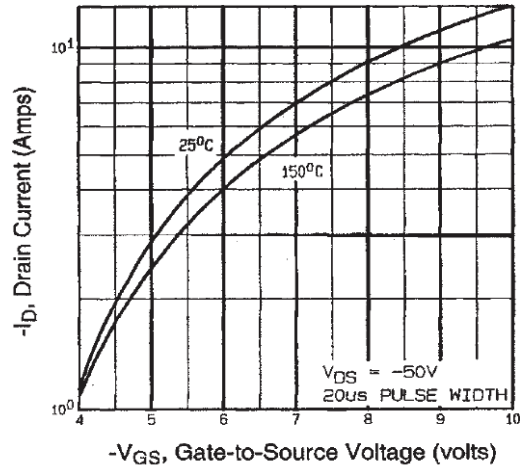


Fig. 3 - Typical Transfer Characteristics

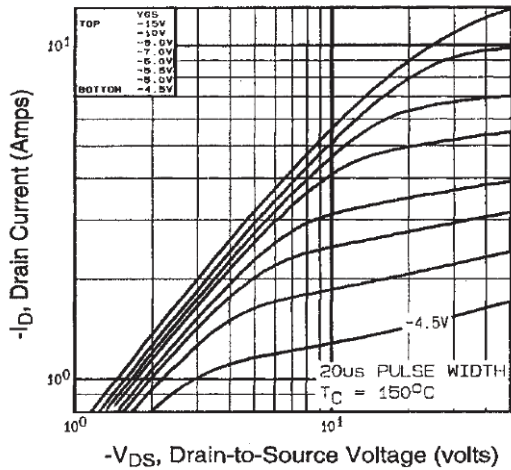


Fig. 2 - Typical Output Characteristics

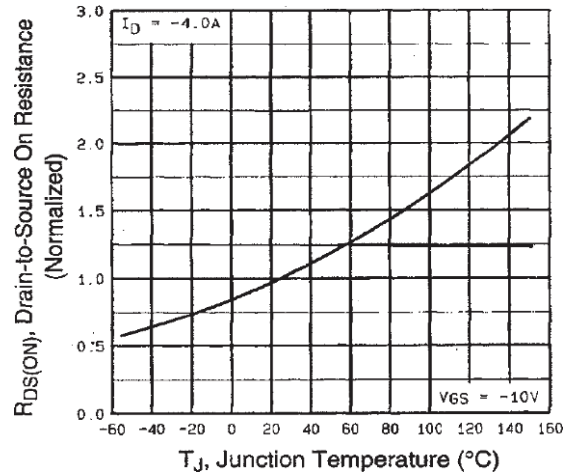


Fig. 4 - Normalized On-Resistance vs. Temperature

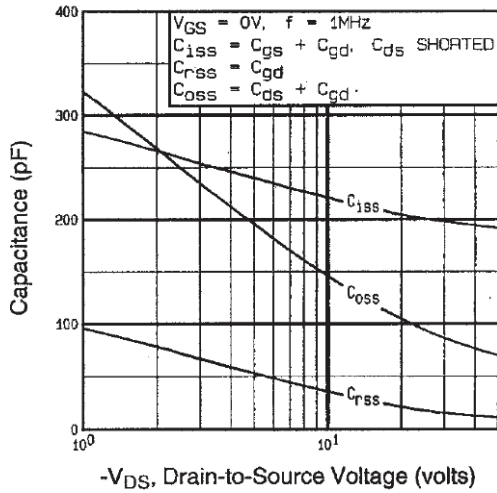


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

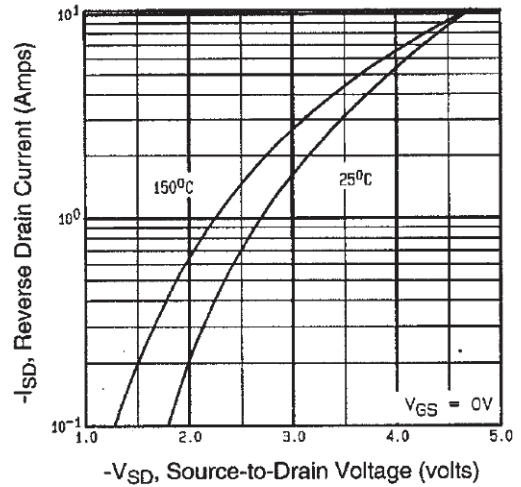


Fig. 7 - Typical Source-Drain Diode Forward Voltage



Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

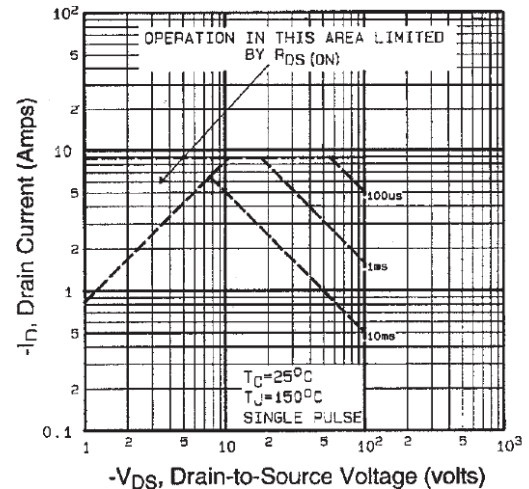


Fig. 8 - Maximum Safe Operating Area

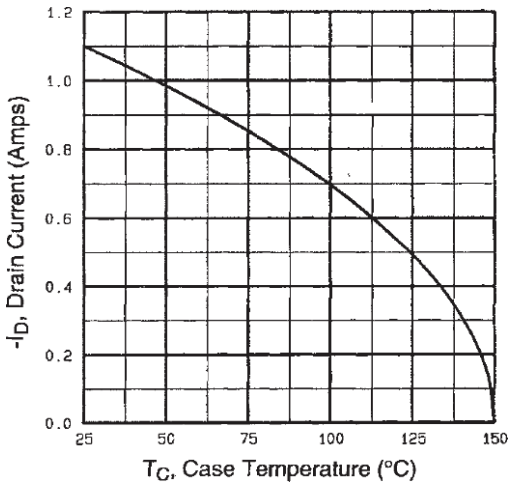


Fig. 9 - Maximum Drain Current vs. Case Temperature

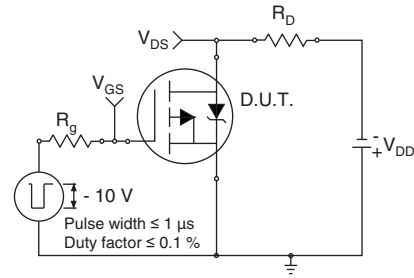


Fig. 10a - Switching Time Test Circuit

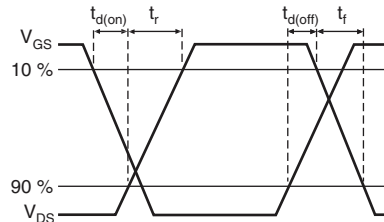


Fig. 10b - Switching Time Waveforms

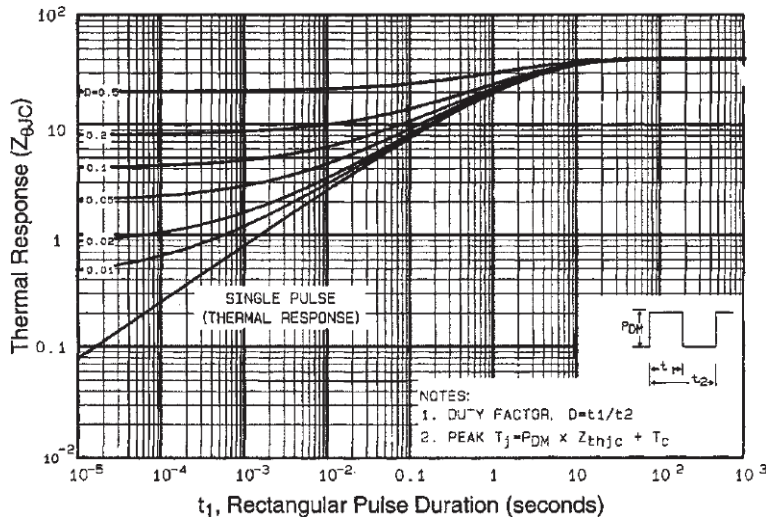


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

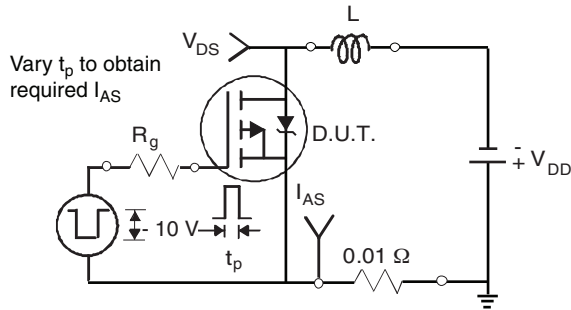


Fig. 12a - Unclamped Inductive Test Circuit

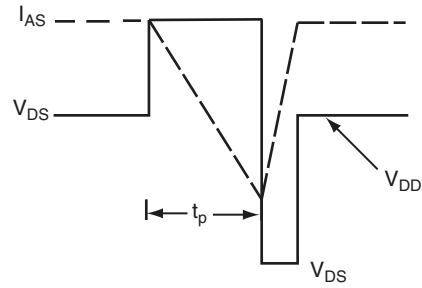


Fig. 12b - Unclamped Inductive Waveforms

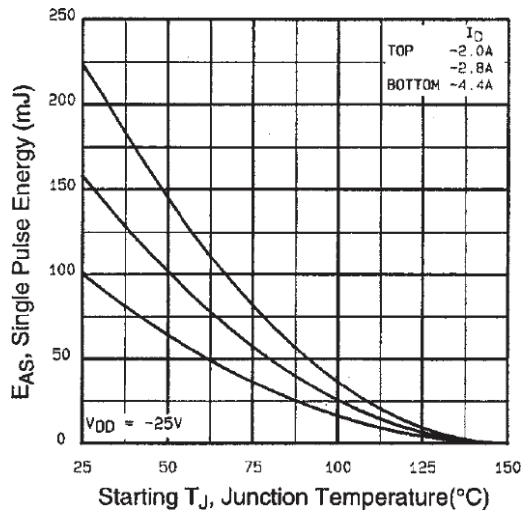


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

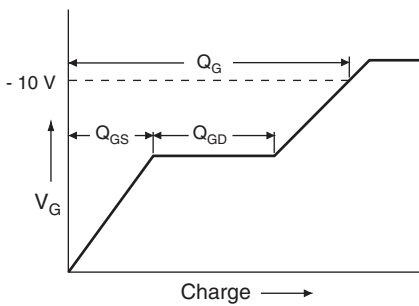


Fig. 13a - Basic Gate Charge Waveform

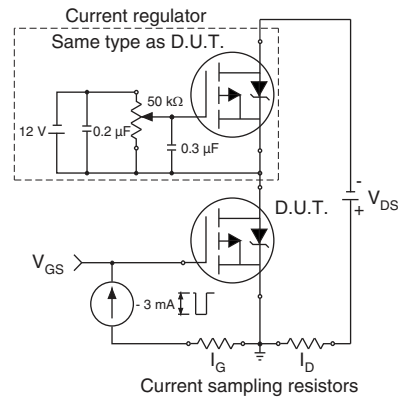
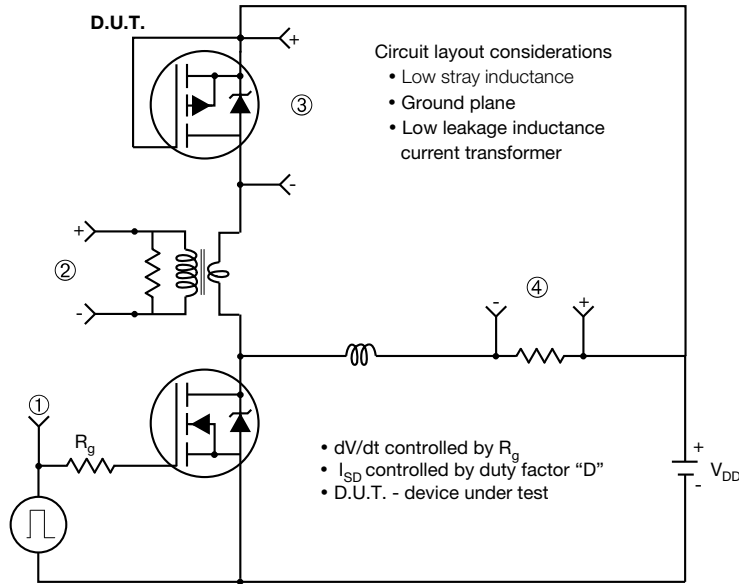


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit



Note
• Compliment N-Channel of D.U.T. for driver



Note
a. $V_{GS} = -5 V$ for logic level and $-3 V$ drive devices

Fig. 14 - For P-Channel

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SOT-223 (HIGH VOLTAGE)



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	1.55	1.80	0.061	0.071
B	0.65	0.85	0.026	0.033
B1	2.95	3.15	0.116	0.124
C	0.25	0.35	0.010	0.014
D	6.30	6.70	0.248	0.264
E	3.30	3.70	0.130	0.146
e	2.30 BSC		0.0905 BSC	
e1	4.60 BSC		0.181 BSC	
H	6.71	7.29	0.264	0.287
L	0.91	-	0.036	-
L1	0.061 BSC		0.0024 BSC	
θ	-	10'	-	10'

ECN: S-82109-Rev. A, 15-Sep-08
DWG: 5969

Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension do not include mold flash.
4. Outline conforms to JEDEC outline TO-261AA.



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